SDLS049B – DECEMBER 1983 – REVISED FEBRUARY 2002

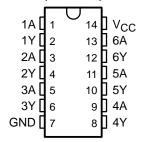
- Operation From Very Slow Edges
- Improved Line-Receiving Characteristics
- High Noise Immunity

description

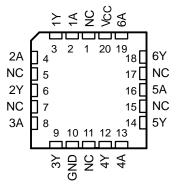
Each circuit functions as an inverter, but because of the Schmitt action, it has different input threshold levels for positive-going (V_{T+}) and negative-going (V_{T-}) signals.

These circuits are temperature compensated and can be triggered from the slowest of input ramps and still give clean, jitter-free output signals.

SN5414, SN54LS14...J OR W PACKAGE SN7414...D, N, OR NS PACKAGE SN74LS14...D, DB, OR N PACKAGE (TOP VIEW)



SN54LS14 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

TA	PACI	(AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN7414N	SN7414N
	PDIP - N	Tube	SN74LS14N	SN74LS14N
		Tube	SN7414D	7414
0°C to 70°C	SOIC - D	Tape and reel	SN7414DR	7414
0 0 10 70 0	3010 - D	Tube	SN74LS14D	LS14
		Tape and reel	SN74LS14DR	L314
	SOP – NS	Tape and reel	SN7414NSR	SN7414
	SSOP – DB	Tape and reel	SN74LS14DBR	LS14
		Tube	SN5414J	SN5414J
	CDIP – J	Tube	SNJ5414J	SNJ5414J
	CDIF = J	Tube	SN54LS14J	SN54LS14J
–55°C to 125°C		Tube	SNJ54LS14J	SNJ54LS14J
	CFP – W	Tube	SNJ5414W	SNJ5414W
	GFF - W	Tube	SNJ54LS14W	SNJ54LS14W
	LCCC – FK	Tube	SNJ54LS14FK	SNJ54LS14FK

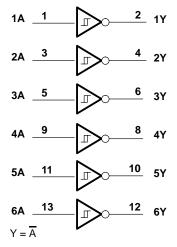
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



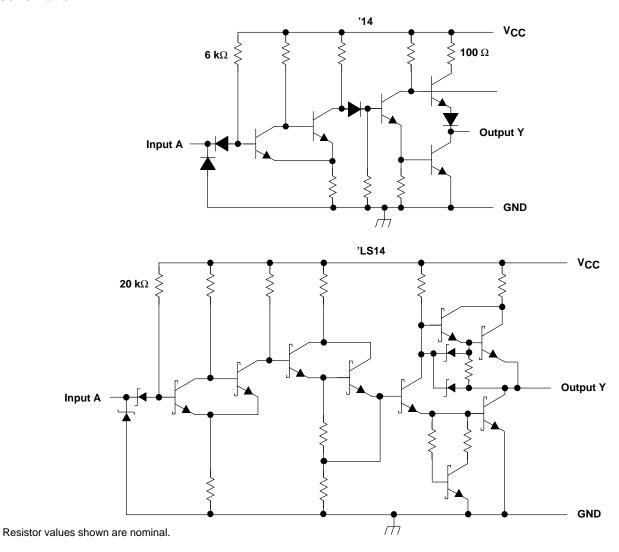
logic diagram (positive logic)



Pin numbers shown are for the D, DB, J, N, NS, and W packages.



schematic





absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	
Input voltage: '14	5.5 V
'LS14	7 V
Package thermal impedance, θ _{JA} (see Note 2): D package	e 86°C/W
DB packa	ge 96°C/W
N package	e 80°C/W
NS packa	ge 76°C/W
Storage temperaturerange, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Voltage values are with respect to network ground terminal.
 - 2. The package termal impedance is calculated in accordance with JESD 51-7

recommended operating conditions

			SN5414		,	SN7414		UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
ІОН	High-level output current			-0.8			-0.8	mA
l _{OL}	Low-level output current			16			16	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDI	TIONS‡		SN5414 SN7414		UNIT
				MIN	TYP§	MAX	
V _{T+}	V _{CC} = 5 V			1.5	1.7	2	V
V_{T-}	V _{CC} = 5 V			0.6	0.9	1.1	V
Hysteresis (V _{T+} – V _T)	V _{CC} = 5 V			0.4	0.8		V
VIK	V _{CC} = MIN,	I _I = -12 mA				-1.5	V
VOH	$V_{CC} = MIN,$	$V_{I} = 0.6 V$,	$I_{OH} = -0.8 \text{ mA}$	2.4	3.4		V
V _{OL}	$V_{CC} = MIN,$	$V_I = 2 V$,	I _{OL} = 16 mA		0.2	0.4	V
I _{T+}	$V_{CC} = 5 V$,	$V_I = V_{T+}$			-0.43		mA
I _T _	$V_{CC} = 5 V$,	$V_I = V_{T-}$			-0.56		mA
lį	$V_{CC} = MAX$,	V _I = 5.5 V				1	mA
I _{IH}	$V_{CC} = MAX$,	$V_{IH} = 2.4 \text{ V}$				40	μΑ
I _{IL}	$V_{CC} = MAX$,	$V_{IL} = 0.4 V$			-0.8	-1.2	mA
los¶	$V_{CC} = MAX$			-18		-55	mA
Іссн	V _{CC} = MAX				22	36	mA
ICCL	$V_{CC} = MAX$				39	60	mA

[‡] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



[§] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[¶] Not more than one output should be shorted at a time.

SDLS049B - DECEMBER 1983 - REVISED FEBRUARY 2002

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		SN5414 SN7414			
	(INPOT) (OUTPO			MIN	TYP	MAX		
^t PLH	Α	V	$R_L = 400 \Omega$, $C_L = 15 pF$		15	22	ns	
tpHL		1	111 - 400 22, OL - 10 PI		15	22	113	

recommended operating conditions

		SN54LS14 SN74LS14					UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
ІОН	High-level output current			-0.4			-0.4	mA
loL	Low-level output current			4			8	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED		TEST SOUDITI	ovet	s	N54LS1	4	S	N74LS1	4	UNIT
PARAMETER		TEST CONDITI	UNSI	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNII
V _{T+}	V _{CC} = 5 V			1.4	1.6	1.9	1.4	1.6	1.9	V
V _T –	V _{CC} = 5 V			0.5	0.8	1	0.5	0.8	1	V
Hysteresis (V _{T+} – V _T –)	V _{CC} = 5 V			0.4	0.8		0.4	0.8		٧
VIK	$V_{CC} = MIN,$	I _I = -18 mA				-1.5			-1.5	V
Vон	$V_{CC} = MIN,$	$V_{I} = 0.5 V$,	$I_{OH} = -0.4 \text{ mA}$	2.5	3.4		2.7	3.4		V
Vol	V _{CC} = MIN,	V _I = -1.9 V	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	V
VOL	VCC = IVIIIA,	V = -1.9 V	$I_{OL} = 8 \text{ mA}$					0.35	0.5	V
I _{T+}	$V_{CC} = 5 V$,	$V_I = V_{T+}$			-0.14			-0.14		mA
I _T _	$V_{CC} = 5 V$,	$V_I = V_{T-}$			-0.18			-0.18		mA
IĮ	$V_{CC} = MAX$,	V _I = 7 V				0.1			0.1	mA
lін	$V_{CC} = MAX$,	$V_{IH} = 2.7 V$				20			20	μΑ
I _{IL}	$V_{CC} = MAX$,	$V_{IL} = 0.4 V$				-0.4			-0.4	mA
los§	$V_{CC} = MAX$			-20		-100	-20		-100	mA
ІССН	$V_{CC} = MAX$				8.6	16		8.6	16	mA
^I CCL	$V_{CC} = MAX$				12	21		12	21	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	Δ	V	$R_1 = 2 k\Omega$, $C_1 = 15 pF$		15	22	ns
tpHL		1	11 - 2 1/22, OL - 10 PI		15	22	113



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

SDLS049B - DECEMBER 1983 - REVISED FEBRUARY 2002

PARAMETER MEASUREMENT INFORMATION **SERIES 54/74 DEVICES** Vcc ○ R_{L} Test Test **Point** S1 ۷сс **Point** From Output VCC **Under Test** (see Note B) (see Note A) From Output R_{L} 1 k Ω **Under Test** (see Note B) From Output Test **Under Test Point** (see Note A) (see Note A) S2 **LOAD CIRCUIT** LOAD CIRCUIT **LOAD CIRCUIT** FOR 2-STATE TOTEM-POLE OUTPUTS FOR OPEN-COLLECTOR OUTPUTS **FOR 3-STATE OUTPUTS High-Level Timing** 1.5 V **Pulse** Input th Low-Level Data **Pulse** Input **VOLTAGE WAVEFORMS VOLTAGE WAVEFORMS PULSE DURATIONS SETUP AND HOLD TIMES** Output 3 V Control .5 V (low-level enabling) Input 1.5 V 0 V **tPZL tPLZ tPLH tPHL** Waveform 1 ≈1.5 V In-Phase − VoH (see Notes C Output and D) (see Note D) Vol ^tPHZ tPZH -^tPHL Waveform 2 V_{OH} - 0.5 V Out-of-Phase ۷он (see Notes C 1.5 V Output 1.5 V 1.5 V and D) (see Note D) · VOL

NOTES: A. C_I includes probe and jig capacitance.

B. All diodes are 1N3064 or equivalent.

VOLTAGE WAVEFORMS

PROPAGATION DELAY TIMES

- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. S1 and S2 are closed for tpLH, tpHL, tpHZ, and tpLZ; S1 is open and S2 is closed for tpZH; S1 is closed and S2 is open for tpZL.

VOLTAGE WAVEFORMS

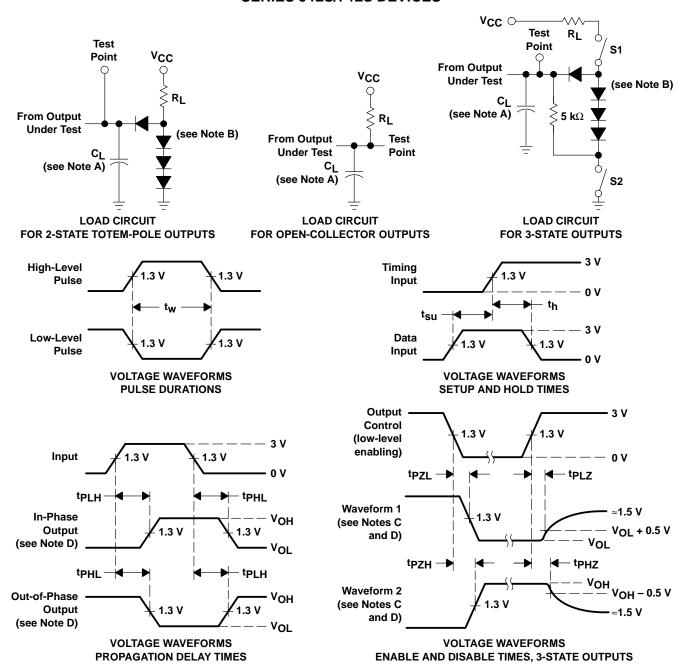
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

- E. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O \approx 50 \Omega$; t_r and $t_f \leq$ 7 ns for Series 54/74 devices and t_r and $t_f \le 2.5$ ns for Series 54S/74S devices.
- F. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION SERIES 54LS/74LS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 - B. All diodes are 1N3064 or equivalent.
 - C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - D. S1 and S2 are closed for tpLH, tpHZ, and tpLZ; S1 is open and S2 is closed for tpZH; S1 is closed and S2 is open for tpZL.
 - E. Phase relationships between inputs and outputs have been chosen arbitrarily for these examples.
 - F. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O \approx 50~\Omega$, $t_f \leq$ 1.5 ns, $t_f \leq$ 2.6 ns.
 - G. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuits and Voltage Waveforms

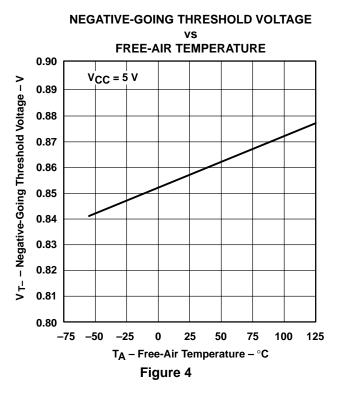


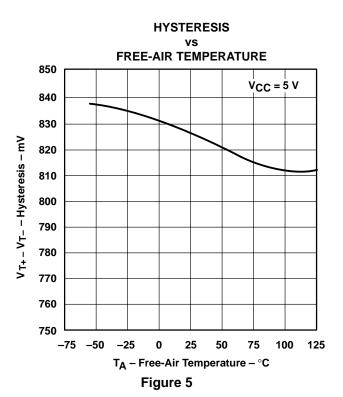
SDLS049B - DECEMBER 1983 - REVISED FEBRUARY 2002

TYPICAL CHARACTERISTICS OF '14 CIRCUITS'

POSITIVE-GOING THRESHOLD VOLTAGE FREE-AIR TEMPERATURE 1.70 $V_{CC} = 5 V$ V_{T+} – Positive-Going Threshold Voltage – V 1.69 1.68 1.67 1.66 1.65 1.64 1.63 1.62 1.61 1.60 25 50 75 100 **–75 –50** -25 0 125 T_A – Free-Air Temperature – $^{\circ}C$

Figure 3

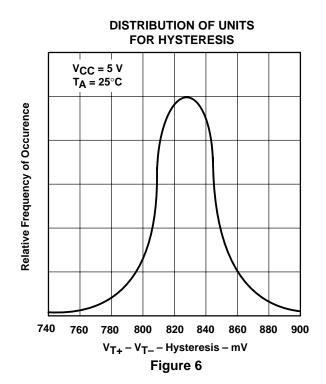


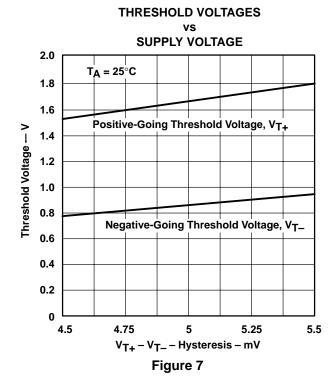


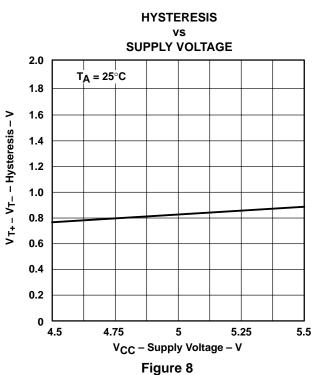
[†] Data for temperatures below 0°C and above 70°C and supply voltage below 4.75 V and above 5.25 V are applicable for SN5414 only.

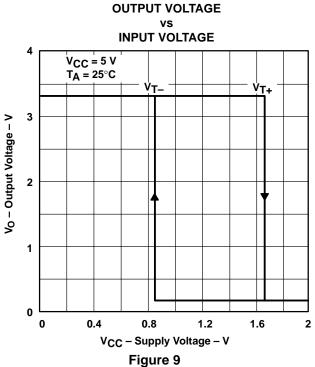


TYPICAL CHARACTERISTICS OF '14 CIRCUITS'







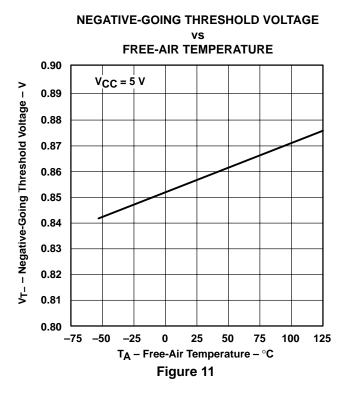


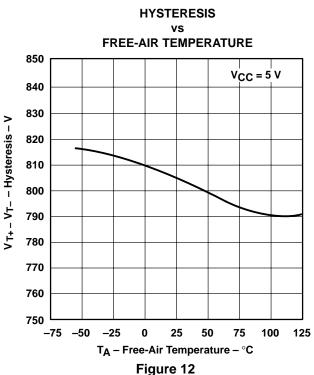
[†] Data for temperatures below 0°C and above 70°C and supply voltage below 4.75 V and above 5.25 V are applicable for SN5414 only.

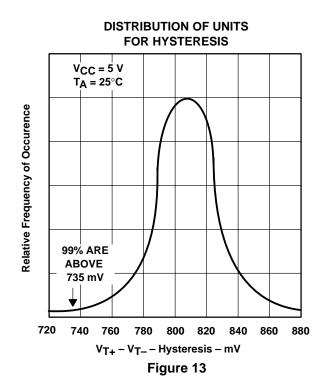


TYPICAL CHARACTERISTICS OF 'LS14 CIRCUITS'

POSITIVE-GOING THRESHOLD VOLTAGE FREE-AIR TEMPERATURE 1.70 $V_{CC} = 5 V$ VT+ - Positive-Going Threshold Voltage - V 1.69 1.68 1.67 1.66 1.65 1.64 1.63 1.62 1.61 1.60 -75 -50 25 50 75 100 125 T_A - Free-Air Temperature - °C Figure 10



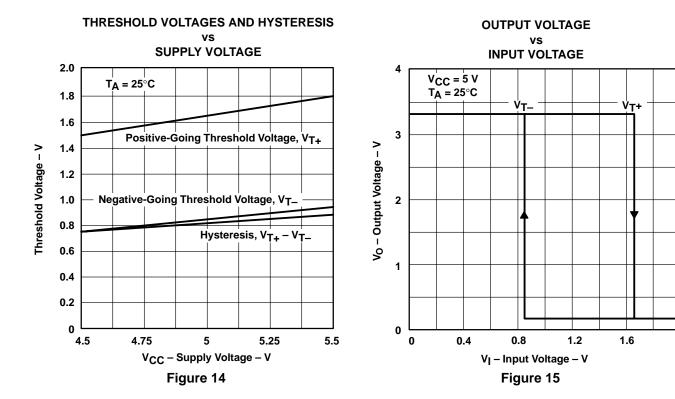




[†] Data for temperatures below 0°C and above 70°C and supply voltage below 4.75 V and above 5.25 V are applicable for SN5414 only.



TYPICAL CHARACTERISTICS OF 'LS14 CIRCUITS'

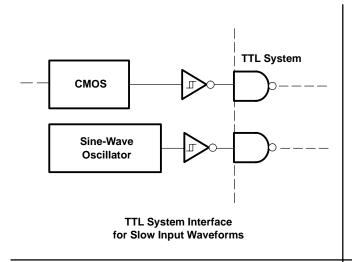


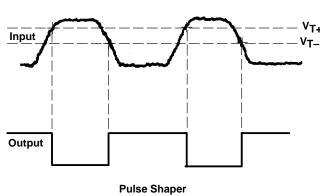
[†] Data for temperatures below 0°C and above 70°C and supply voltage below 4.75 V and above 5.25 V are applicable for SN5414 only.

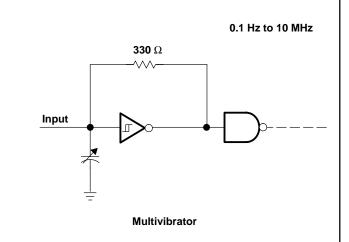


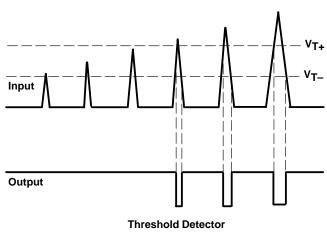
SDLS049B - DECEMBER 1983 - REVISED FEBRUARY 2002

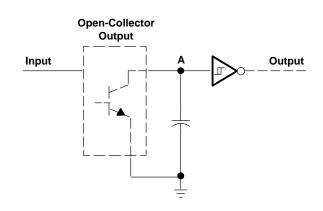
TYPICAL APPLICATION DATA

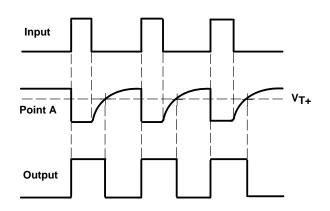












Pulse Stretcher





www.ti.com 15-Oct-2009

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9665801Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9665801QCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
5962-9665801QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
5962-9665801VCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
5962-9665801VDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/31302BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN5414J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54LS14J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN7414D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7414DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7414DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7414DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7414DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7414DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7414N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN7414N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7414NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN7414NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7414NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7414NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS14D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS14DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS14DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS14DBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS14DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS14DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS14DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS14DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS14DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM

PACKAGE OPTION ADDENDUM

www.ti.com 15-Oct-2009

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						no Sb/Br)		
SN74LS14N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS14N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS14NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS14NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS14NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS14NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ5414J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ5414W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS14FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS14J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS14W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.





11-Mar-2008

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN7414DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN7414NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS14DBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LS14DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS14NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN7414DR	SOIC	D	14	2500	346.0	346.0	33.0
SN7414NSR	SO	NS	14	2000	346.0	346.0	33.0
SN74LS14DBR	SSOP	DB	14	2000	346.0	346.0	33.0
SN74LS14DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS14NSR	SO	NS	14	2000	346.0	346.0	33.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

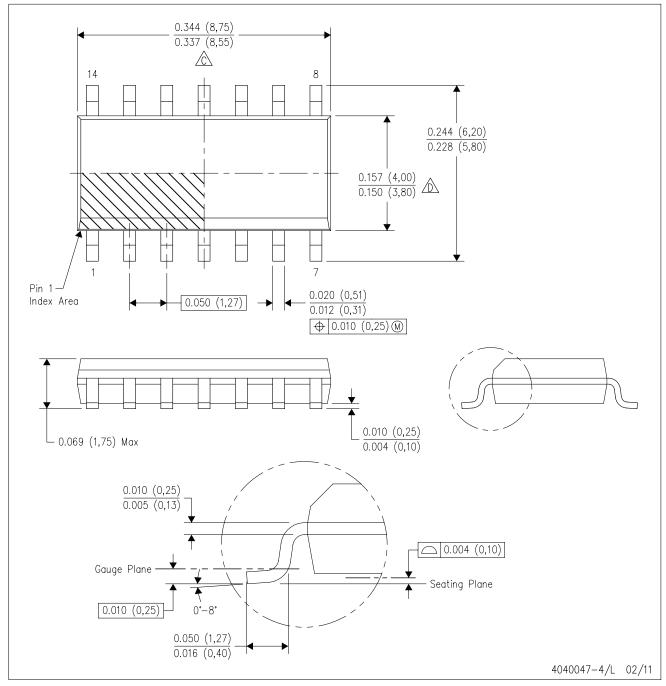


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

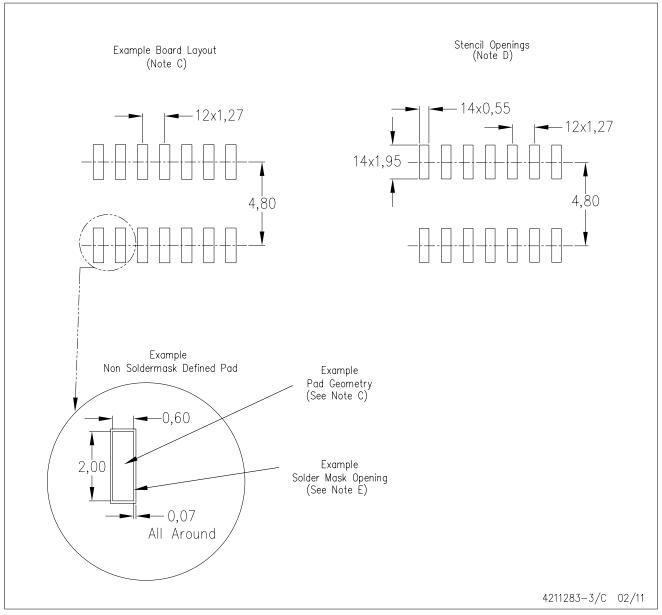


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications			
Audio	www.ti.com/audio	Communications and Telecom	www.ti.com/communications		
Amplifiers	amplifier.ti.com	Computers and Peripherals	www.ti.com/computers		
Data Converters	dataconverter.ti.com	Consumer Electronics	www.ti.com/consumer-apps		
DLP® Products	www.dlp.com	Energy and Lighting	www.ti.com/energy		
DSP	dsp.ti.com	Industrial	www.ti.com/industrial		
Clocks and Timers	www.ti.com/clocks	Medical	www.ti.com/medical		
Interface	interface.ti.com	Security	www.ti.com/security		
Logic	logic.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense		
Power Mgmt	power.ti.com	Transportation and Automotive	www.ti.com/automotive		
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video		
RFID	www.ti-rfid.com	Wireless	www.ti.com/wireless-apps		
RF/IF and ZigBee® Solutions	www.ti.com/lprf				

TI E2E Community Home Page

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2011, Texas Instruments Incorporated

e2e.ti.com